

A SURFACE MOUNT SOLDER METHOD AND APPARATUS
FOR DECOUPLING CAPACITANCE AND
PROCESS OF MAKING

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ABSTRACT OF THE DISCLOSURE

10 A system to package high performance microelectronic devices, such as
processors, responds to component transients. In one embodiment, the system
includes a decoupling capacitor that is disposed between a Vcc electrical bump and
a Vss electrical bump. The decoupling capacitor has Vcc and Vss terminals. The
Vcc and Vss terminals share electrical pads with the Vcc electrical bump and the
Vss electrical bump. A simple current loop is created that improves the power
delivery for the system.

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